

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 20 of the application as follows:

ABSTRACT OF THE DISCLOSURE

An improved wire bond is provided with the bond pads of semiconductor devices and the lead fingers of lead frames or an improved ~~conductor~~ conductive lead of a TAB tape bond with the bond pad of a semiconductor device. More specifically, an improved wire bond is described wherein the bond pad on a surface of the semiconductor device comprises a layer of copper and at least one layer of metal and/or at least a barrier layer of material between the copper layer and one layer of metal on the copper layer to form a bond pad.